OSRAM GR CSSRML.24 **Datasheet**

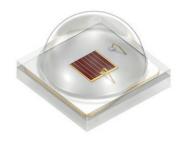




OSLON® Optimal

GR CSSRML.24

A brand new family of LEDs with our ams OSRAM's latest chip technology, delivering significant performance upgrades. The OSLON® Optimal strikes a perfect balance of performance and cost along with proven robustness, high reliability and long lifetime.





Applications

- Agriculture & Horticulture
- Entertainment

- Indoor Lighting
- Outdoor & Industrial Lighting

Features

- Package: SMT ceramic package with silicone lens
- Typ. Radiation: 120° (Lambertian emitter)
- ESD: 8 kV acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 3B)
- Radiant Flux: typ. 485 mW (color bin 5-7)
- Radiant effciency: typ 66.3%
- Photon Flux: typ. 2.58 umol/s
- Photon Flux Efficacy: typ. 3.53 umol/J



Ordering Information				
Туре	Total radiant flux ¹⁾ $I_F = 350 \text{ mA}$ Φ_E	Ordering Code		
GR CSSRML.24-TOUL-47-1	415 565 mW	Q65113A5762		
GR CSSRML.24-UJUL-57-1	450 565 mW	Q65113A5994		



Maximum Ratings			
Parameter	Symbol		Values
Operating Temperature	T _{op}	min.	-40 °C
		max.	125 °C
Storage Temperature	T _{stg}	min.	-40 °C
	0.9	max.	125 °C
Junction Temperature	T _j	max.	135 °C
Forward current	I _F	min.	30 mA
	·	max.	1000 mA
Surge Current	I _{FS}	max.	2000 mA
$t \le 10 \ \mu s; D = 0.005; T_{J} = 25 \ ^{\circ}C$			
Reverse voltage 2)	V_R		Not designed for
			reverse operation
ESD withstand voltage	V _{ESD}		8 kV
acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 3B)	LOD		



Characteristics

 $I_F = 350 \text{ mA}; T_J = 25 \text{ }^{\circ}\text{C}$

Parameter	Symbol		Values
Peak Wavelength	$\lambda_{\sf peak}$	typ.	640 nm
Dominant Wavelength 3)	λ_{dom}	min.	620 nm
$I_{F} = 350 \text{ mA}$		typ.	630 nm
		max.	636 nm
Spectral Bandwidth at 50% I _{rel,max}	$\Delta \lambda$	typ.	15 nm
Viewing angle at 50% I _v	2φ	typ.	120 °
Forward Voltage 4)	V _F	min.	1.90 V
I _F = 350 mA	·	typ.	2.09 V
		max.	2.20 V
Reverse current 2)	I _R		Not designed for reverse operation
Electrical thermal resistance junction/solderpoint with efficiency η_e = 66 %	$R_{ ext{thJS elec.}}$	typ.	2.1 K / W



Brig	htness Gro	oups						
Group	Total radiant flux $^{1)}$ I _F = 350 mA	Total radiant flux ¹⁾ I _F = 350 mA	PPF *	PPF*	PPF/W*	PF **	PF **	PF/W **
	min.	max.	min.	max.	typ.	min.	max.	typ.
	Φ_{E}	Φ_{E}	Φ_{p}	Фр		$\Phi_{p,b}$	$\boldsymbol{\Phi}_{p,b}$	
ТО	415 mW	450 mW	2.21 µmol/s	2.40 µmol/s	3.15 µmol/J	2.21 µmol/s	2.40 µmol/s	3.15 µmol/J
UJ	450 mW	485 mW	2.40 μmol/s	2.58 µmol/s	3.40 µmol/J	2.40 µmol/s	2.58 μmol/s	3.41 µmol/J
UK	485 mW	525 mW	2.58 μmol/s	2.79 µmol/s	3.67 µmol/J	2.58 µmol/s	2.80 μmol/s	3.68 μmol/J
UL	525 mW	565 mW	2.79 µmol/s	3.01 µmol/s	3.97 µmol/J	2.80 µmol/s	3.01 µmol/s	3.97 µmol/J

Note: [*] Photosynthetic Photon Flux includes wavelengths between 400 and 700 nm

Note: [**] Photon Flux includes wavelengths between 280 and 800 nm Note: PPF and PF values are for reference only

Forward Voltage Groups

Group Forward Voltage $^{4)}$ I _F = 350 mA min. V _F		Forward Voltage ⁴⁾ I _F = 350 mA max. V _F	
E2	1.90 V	2.00 V	
F1	2.00 V	2.10 V	
F2	2.10 V	2.20 V	

Wavelength Groups

Group	Dominant Wavelength 3)	Dominant Wavelength 3)	th 3)	
	I _F = 350 mA	I _F = 350 mA		
	min.	max.		
	$\lambda_{\sf dom}$	λ_{dom}		
4	620 nm	624 nm		
5	624 nm	628 nm		
6	628 nm	632 nm		
7	632 nm	636 nm		



Group Name on Label

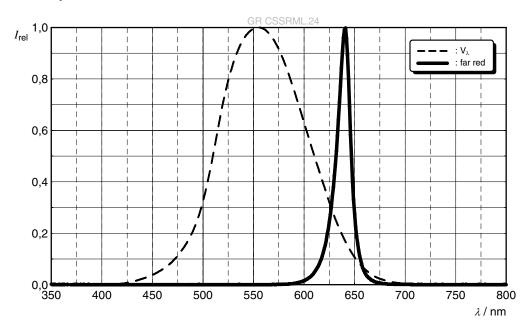
Example: TO-4-E2

Brightness	Wavelength	Forward Voltage	
TO	4	E2	



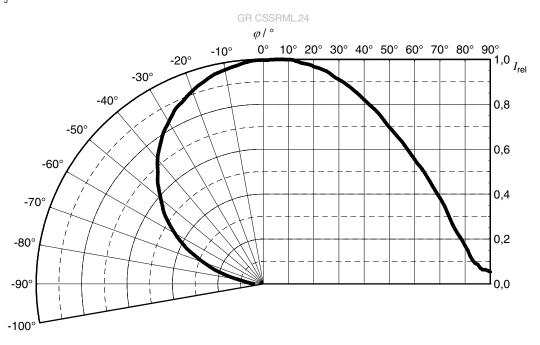
Relative Spectral Emission 5)

 I_{rel} = f (λ); I_F = 350 mA; T_J = 25 °C



Radiation Characteristics 5)

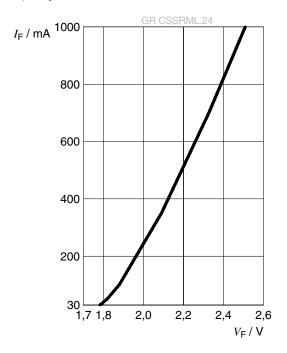
 $I_{rel} = f (\phi); T_J = 25 °C$





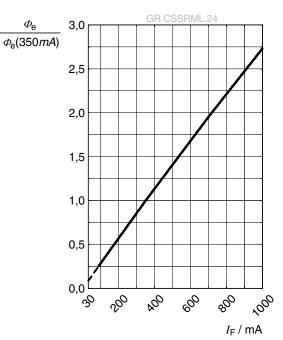
Forward current 5)

$$I_F = f(V_F); T_J = 25 °C$$



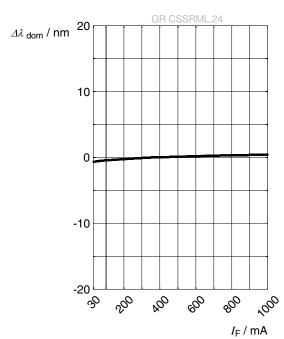
Relative Radiant Power 5), 6)

$$\Phi_{\rm E}/\Phi_{\rm E}(350 \text{ mA}) = f(I_{\rm F}); T_{\rm J} = 25 \,^{\circ}\text{C}$$



Dominant Wavelength 5)

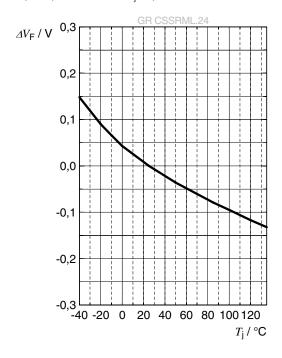
$$\Delta\lambda_{dom} = f(I_F); T_J = 25 \text{ }^{\circ}\text{C}$$





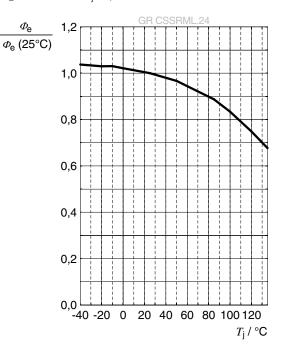
Forward Voltage 5)

$$\Delta V_{_F} = V_{_F} - V_{_F} (25~^{\circ}C) = f(T_{_j}); I_{_F} = 350~mA$$



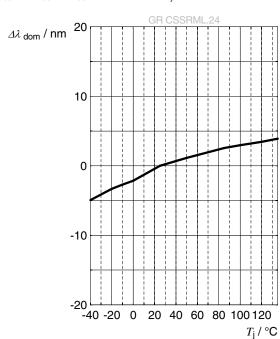
Relative Radiant Power 5)

$$\Phi_{\rm E}/\Phi_{\rm E}(25~{\rm ^{\circ}C}) = f(T_{\rm i}); I_{\rm E} = 350~{\rm mA}$$



Dominant Wavelength 5)

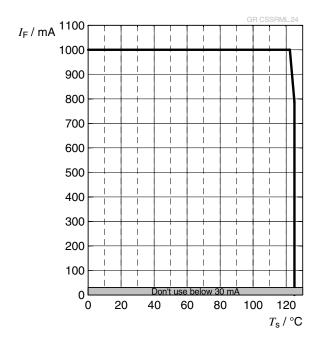
$$\Delta \lambda_{\text{dom}} = \lambda_{\text{dom}} - \lambda_{\text{dom}} (25 \ ^{\circ}\text{C}) = \text{f(T_j); I_F} = 350 \ \text{mA}$$





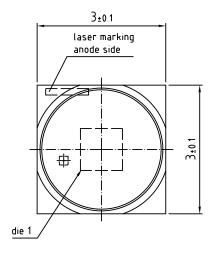
Max. Permissible Forward Current 7)

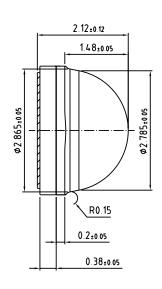
 $I_F = f(T)$

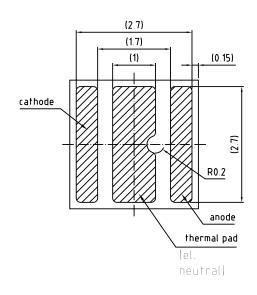




Dimensional Drawing 8)







C69062-A0014-A1-01

Further Information:

Approximate Weight: 27.5 mg

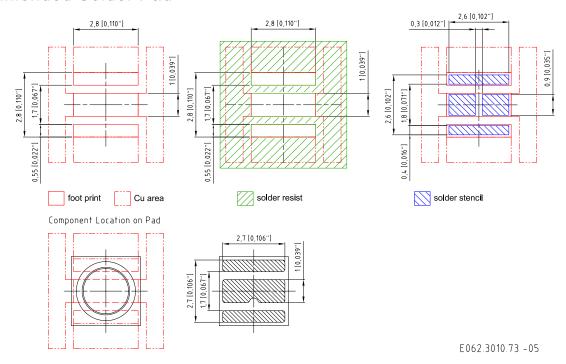
Package marking: Anode

ESD advice: The device is protected by ESD device which is connected in parallel to the

Chip.



Recommended Solder Pad 8)

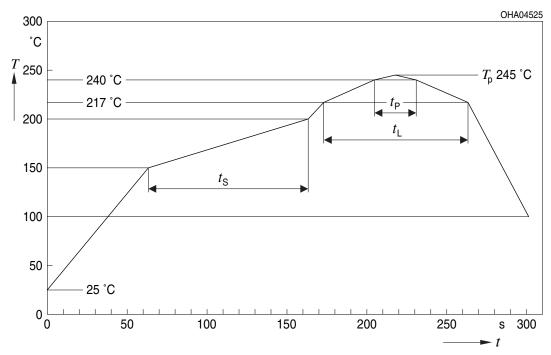


For superior solder joint connectivity results we recommend soldering under standard nitrogen atmosphere. Further information can be found in our Application Note: "Handling and Processing Details for Ceramic LEDs".



Reflow Soldering Profile

Product complies to MSL Level 2 acc. to JEDEC J-STD-020E



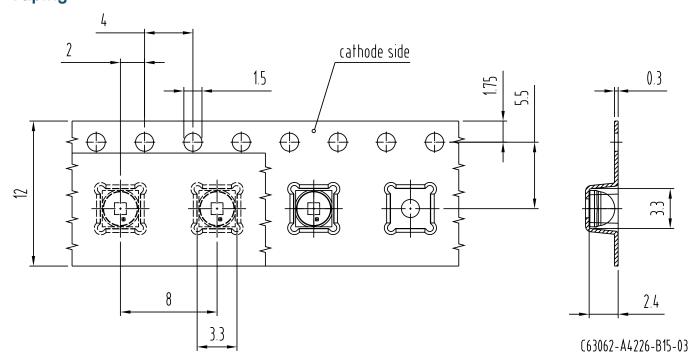
Profile Feature	Symbol	Symbol Pb-Free (SnAgCu) Ass		embly Unit	
		Minimum	Recommendation	Maximum	
Ramp-up rate to preheat*) 25 °C to 150 °C			2	3	K/s
Time t_s T_{Smin} to T_{Smax}	t _s	60	100	120	S
Ramp-up rate to peak $^{*)}$ T _{Smax} to T _P			2	3	K/s
Liquidus temperature	T_{L}		217		°C
Time above liquidus temperature	t _L		80	100	S
Peak temperature	T_{P}		245	260	°C
Time within 5 °C of the specified peak temperature T _p - 5 K	t _P	10	20	30	S
Ramp-down rate* T _P to 100 °C			3	6	K/s
Time 25 °C to T _P				480	S

All temperatures refer to the center of the package, measured on the top of the component

^{*} slope calculation DT/Dt: Dt max. 5 s; fulfillment for the whole T-range

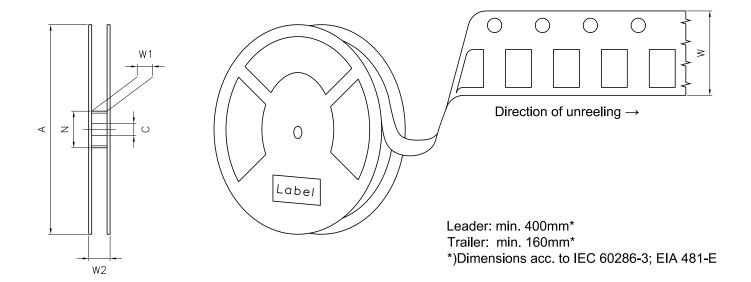


Taping 8)





Tape and Reel 9)

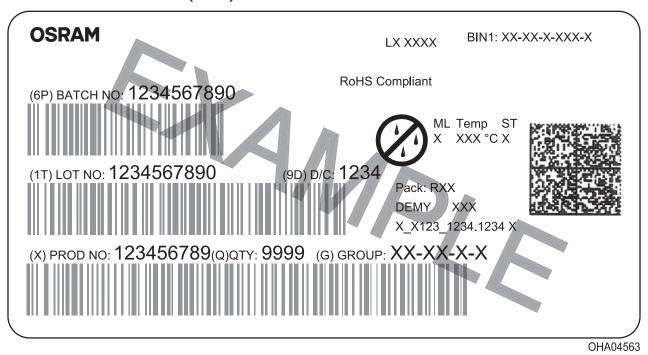


Reel Dimensions

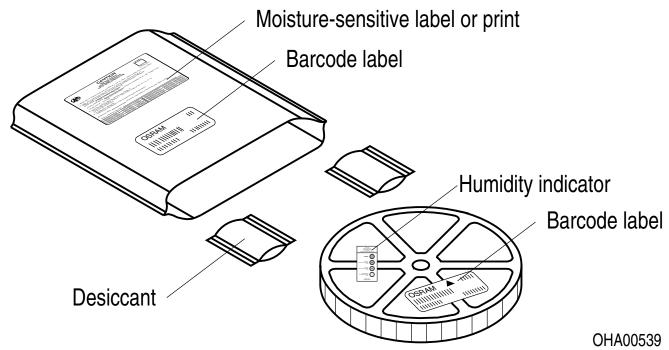
Α	W	N_{\min}	W_1	$W_{2\text{max}}$	Pieces per PU
330 mm	12 + 0.3 / - 0.1 mm	60 mm	12.4 + 2 mm	18.4 mm	3000



Barcode-Product-Label (BPL)



Dry Packing Process and Materials



Moisture-sensitive product is packed in a dry bag containing desiccant and a humidity card according JEDEC-STD-033.



Notes

The evaluation of eye safety occurs according to the standard IEC 62471:2006 (photo biological safety of lamps and lamp systems). Within the risk grouping system of this IEC standard, the device specified in this data sheet fall into the class exempt group (exposure time 10000 s). Under real circumstances (for exposure time, conditions of the eye pupils, observation distance), it is assumed that no endangerment to the eye exists from these devices. As a matter of principle, however, it should be mentioned that intense light sources have a high secondary exposure potential due to their blinding effect. When looking at bright light sources (e.g. headlights), temporary reduction in visual acuity and afterimages can occur, leading to irritation, annoyance, visual impairment, and even accidents, depending on the situation.

Subcomponents of this device contain, in addition to other substances, metal filled materials including silver. Metal filled materials can be affected by environments that contain traces of aggressive substances. Therefore, we recommend that customers minimize device exposure to aggressive substances during storage, production, and use. Devices that showed visible discoloration when tested using the described tests above did show no performance deviations within failure limits during the stated test duration. Respective failure limits are described in the IEC60810.

This device is designed for specific/recommended applications only. Please consult OSRAM Opto Semiconductors Sales Staff in advance for detailed information on other non-recommended applications (e.g. automotive).

Change management for this component is aligned with the requirements of the lighting market.

For further application related information please visit https://ams-osram.com/support/application-notes



Disclaimer

Attention please!

The information describes the type of component and shall not be considered as assured characteristics. Terms of delivery and rights to change design reserved. Due to technical requirements components may contain dangerous substances.

For information on the types in question please contact our Sales Organization.

If printed or downloaded, please find the latest version on our website.

Packing

Please use the recycling operators known to you. We can also help you – get in touch with your nearest sales office. By agreement we will take packing material back, if it is sorted. You must bear the costs of transport. For packing material that is returned to us unsorted or which we are not obliged to accept, we shall have to invoice you for any costs incurred.

Product and functional safety devices/applications or medical devices/applications

Our components are not developed, constructed or tested for the application as safety relevant component or for the application in medical devices.

Our products are not qualified at module and system level for such application.

In case buyer – or customer supplied by buyer – considers using our components in product safety devices/ applications or medical devices/applications, buyer and/or customer has to inform our local sales partner immediately and we and buyer and /or customer will analyze and coordinate the customer-specific request between us and buyer and/or customer.



Glossary

- Brightness: Brightness values are measured during a current pulse of typically 10 ms, with a tolerance of +/- 7%.
- 2) Reverse Operation: Not designed for reverse operation. Continuous reverse operation can cause migration and damage of the device.
- 3) Wavelength: The wavelength is measured at a current pulse of typically 10 ms, with a tolerance of ± 0.5 nm.
- Forward Voltage: The Forward voltage is measured during a current pulse duration of typically 1 ms with a tolerance of $\pm 0.05V$.
- Typical Values: Due to the special conditions of the manufacturing processes of semiconductor devices, the typical data or calculated correlations of technical parameters can only reflect statistical figures. These do not necessarily correspond to the actual parameters of each single product, which could differ from the typical data and calculated correlations or the typical characteristic line. If requested, e.g. because of technical improvements, these typ. data will be changed without any further notice.
- 6) Characteristic curve: In the range where the line of the graph is broken, you must expect higher differences between single devices within one packing unit.
- 7) Thermal Resistance: Rth max is based on statistic values (6 σ) used for Derating.
- 8) Tolerance of Measure: Unless otherwise noted in drawing, tolerances are specified with ±0.1 and dimensions are specified in mm.
- 9) Tape and Reel: All dimensions and tolerances are specified acc. IEC 60286-3 and specified in mm.



Revision History

Version	Date	Change
1.0	2023-04-07	Initial Version
1.0	2023-04-11	Initial Version
1.1	2024-11-08	Description



EU RoHS and China RoHS compliant product 此产品符合欧盟 RoHS 指令的要求; 按照中国的相关法规和标准, 不含有毒有害物质或元素。

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